- *EPIC*[™] (Enhanced-Performance Implanted CMOS) Submicron Process
- I_{off} Supports Partial-Power-Down Mode Operation
- Supports 5-V V_{CC} Operation
- Package Options Include Plastic Thin Shrink Small-Outline (DCT, DCU) Packages

description

This dual bus buffer gate is designed for 1.65-V to 5.5-V V_{CC} operation.

The SN74LVC2G126 is a dual bus driver/line driver with 3-state outputs. The outputs are disabled when the associated output-enable (OE) input is low.

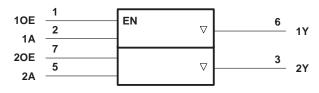
To ensure the high-impedance state during power up or power down, OE should be tied to GND through a pulldown resistor; the minimum value of the resistor is determined by the current-sourcing capability of the driver.

This device is fully specified for partial-power-down applications using I_{off}. The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

The SN74LVC2G126 is characterized for operation from -40°C to 85°C.

FUNCTION TABLE (each buffer)							
INPU	OUTPUT						
OE	Α	Y					
Н	Н	Н					
Н	L	L					
L	Х	Z					

logic symbol[†]



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.



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DCT OR DCU PACKAGE (TOP VIEW) 10E 1 8 V_{CC} 1A 2 7 20E 2Y 3 6 1Y GND 4 5 2A

SN74LVC2G126

DUAL BUS BUFFER GATE WITH 3-STATE OUTPUTS

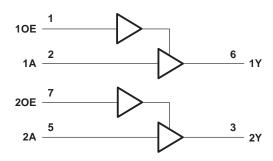
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SN74LVC2G126 DUAL BUS BUFFER GATE WITH 3-STATE OUTPUTS

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logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V _{CC} Input voltage range, V _I (see Note 1) Output voltage range, V _O (see Notes 1 and 2)	–0.5 V to 6.5 V
Input clamp current, I_{IK} (V _I < 0)	
Output clamp current, I _{OK} (V _O < 0)	
Continuous output current, I _O	±50 mA
Continuous current through V _{CC} or GND	±100 mA
Package thermal impedance, θ_{JA} (see Note 3): DCT package	
DCU package	
Storage temperature range, T _{stg}	

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. The value of V_{CC} is provided in the recommended operating conditions table.

3. The package thermal impedance is calculated in accordance with JESD 51.



recommended operating conditions (see Note 4)

			MIN	MAX	UNI	
	Supply voltage	Operating	1.65	5.5	V	
Vcc	Supply voltage	Data retention only	1.5		V	
	High-level input voltage	V _{CC} = 1.65 V to 1.95 V	$0.65 \times V_{CC}$			
\ <i>\</i>		V_{CC} = 2.3 V to 2.7 V	1.7		V	
VIН		$V_{CC} = 3 V \text{ to } 3.6 V$	2		v	
		$V_{CC} = 4.5 \text{ V} \text{ to } 5.5 \text{ V}$	$0.7 \times V_{CC}$			
		V _{CC} = 1.65 V to 1.95 V		$0.35 \times V_{CC}$		
Ma	Low-level input voltage $\frac{V_{CC} = 2.3 \text{ V to }}{V_{CC} = 3 \text{ V to }}$	V _{CC} = 2.3 V to 2.7 V		0.7	v	
VIL		$V_{CC} = 3 V \text{ to } 3.6 V$		0.8		
		V_{CC} = 4.5 V to 5.5 V		$0.3 \times V_{CC}$		
VI	Input voltage		0	5.5	V	
Vo	Output voltage		0	VCC	V	
	High-level output current	V _{CC} = 1.65 V		-4		
		V _{CC} = 2.3 V		-8	mA	
ЮН				-16		
		V _{CC} = 3 V		-24		
		V _{CC} = 4.5 V		-32		
	Low-level output current	V _{CC} = 1.65 V		4		
		V _{CC} = 2.3 V		8		
IOL				16	mA	
		$V_{CC} = 3 V$		24		
		V _{CC} = 4.5 V	32			
	Input transition rise or fall rate	V_{CC} = 1.8 V ± 0.15 V, 2.5 V ± 0.2 V		20		
$\Delta t / \Delta v$		$V_{CC} = 3.3 V \pm 0.3 V$		10	ns/\	
		$V_{CC} = 5 V \pm 0.5 V$				
TA	Operating free-air temperature	•	-40	85	°C	

NOTE 4: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



SN74LVC2G126 **DUAL BUS BUFFER GATE** WITH 3-STATE OUTPUTS

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PA	RAMETER	TEST CONDITIONS	Vcc	MIN	TYP†	MAX	UNIT
		I _{OH} = -100 μA	1.65 V to 5.5 V	V _{CC} -0.1			
		$I_{OH} = -4 \text{ mA}$	1.65 V	1.2			
		$I_{OH} = -8 \text{ mA}$	2.3 V	1.9			
VOH		$I_{OH} = -16 \text{ mA}$		2.4			V
		I _{OH} = -24 mA	3 V	2.3			
		$I_{OH} = -32 \text{ mA}$	4.5 V	3.8			
		I _{OL} = 100 μA	1.65 V to 5.5 V			0.1	
		I _{OL} = 4 mA	1.65 V			0.45	
		I _{OL} = 8 mA	2.3 V			0.3	V
VOL		I _{OL} = 16 mA	3 V			0.4	V
		I _{OL} = 24 mA	3 V			0.55	
		I _{OL} = 32 mA	4.5 V			0.55	
I	A or OE inputs	V _I = 5.5 V or GND	0 to 5.5 V			±5	μΑ
loff	-	$V_{I} \text{ or } V_{O} = 5.5 \text{ V}$	0			±10	μΑ
ICC		$V_{I} = 5.5 V \text{ or GND}, \qquad I_{O} = 0$	1.65 V to 5.5 V			10	μΑ
∆lCC		One input at V_{CC} – 0.6 V, Other inputs at V_{CC} or GND	3 V to 5.5 V			500	μΑ
Ci		$V_{I} = V_{CC}$ or GND	3.3 V				pF

[†] All typical values are at V_{CC} = 3.3 V, T_A = 25°C.

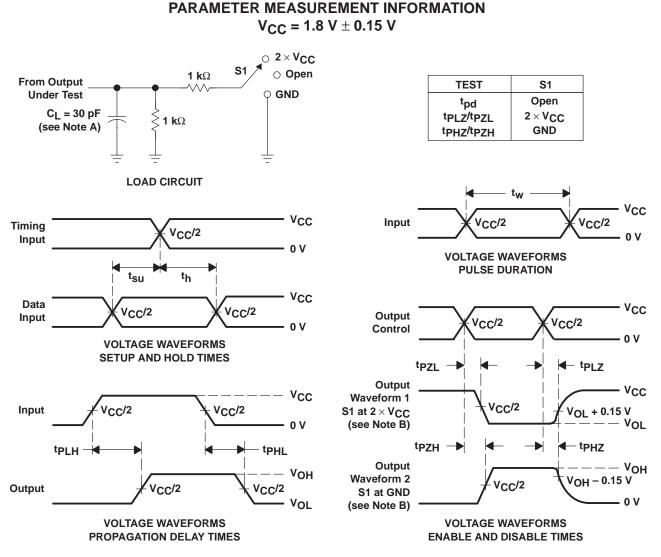
switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figures 1 through 4)

PARAME	PARAMETER	FROM TO (INPUT) (OUTPUT)		V _{CC} = 1.8 V ± 0.15 V				V _{CC} = 2.5 V ± 0.2 V		V _{CC} = 3.3 V ± 0.3 V		V _{CC} = 5 V ± 0.5 V		UNIT	
			MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX					
^t pd		A	Y									ns			
ten		OE	Y									ns			
^t dis		OE	Y									ns			

operating characteristics, $T_A = 25^{\circ}C$

		PARAMETER	TEST CONDITIONS	V _{CC} = 1.8 V	V _{CC} = 2.5 V	V _{CC} = 3.3 V	V _{CC} = 5 V	UNIT
			TEST CONDITIONS	TYP	TYP	TYP	TYP	UNIT
	C _{pd}	Power dissipation capacitance	f = 10 MHz					pF





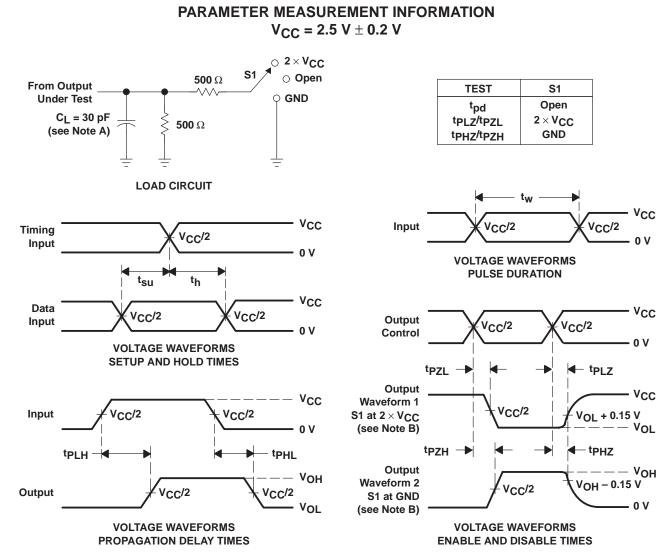
- NOTES: A. CL includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_f ≤ 2 ns, t_f ≤ 2 ns.
 - D. The outputs are measured one at a time with one transition per measurement.
 - E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - F. tpzL and tpzH are the same as t_{en} .
 - G. tp[H and tpH] are the same as t_{pd} .

Figure 1. Load Circuit and Voltage Waveforms

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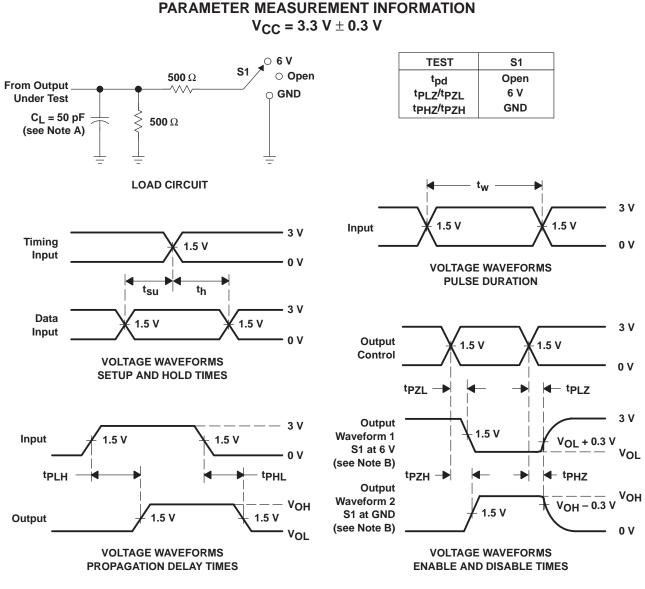
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- NOTES: A. CL includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_Q = 50 Ω, t_f ≤ 2 ns, t_f ≤ 2 ns.
 - D. The outputs are measured one at a time with one transition per measurement.
 - E. tPLZ and tPHZ are the same as tdis.
 - F. tpzL and tpzH are the same as ten.
 - G. tPLH and tPHL are the same as tpd.

Figure 2. Load Circuit and Voltage Waveforms





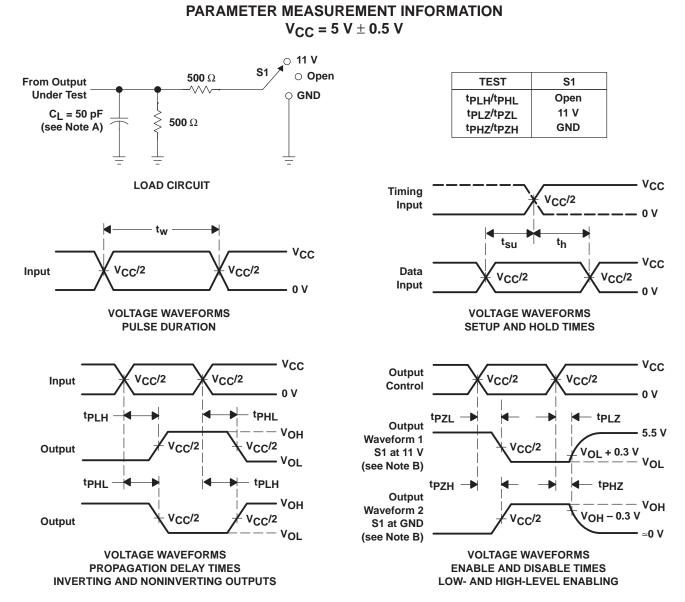
NOTES: A. CL includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_O = 50 Ω , t_f \leq 2.5 ns, t_f \leq 2.5 ns.
- D. The outputs are measured one at a time with one transition per measurement.
- E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
- F. t_{PZL} and t_{PZH} are the same as t_{en} .
- G. tPLH and tPHL are the same as tpd.

Figure 3. Load Circuit and Voltage Waveforms

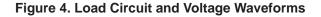






NOTES: A. CL includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control.
 Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 All input pulses are supplied by generators basing the following characteristics: PRP < 10 MHz, Zo = 50.0 t, < 2.5 ns. tr < 2.5 ns.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_O = 50 Ω , t_f \leq 2.5 ns, t_f \leq 2.5 ns.
- D. The outputs are measured one at a time with one transition per measurement.
- E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
- F. t_{PZL} and t_{PZH} are the same as t_{en} .
- G. tPLH and tPHL are the same as tpd.





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